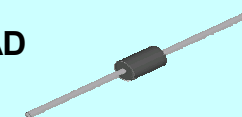


MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

Package: DO-201 AD



Part Number:

Description: General Purpose, Fast and Ultrafast

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD WIRE	O2 Free Cu Wire	742.756	67.52%	Cu Oxygen	7440-50-8 7782-44-7	99,9 min 0,0015 max	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Epoxy Moulding Compound	337.570	30.69%	SiO2 (Fused Silica)	60676-86-0	70-75	< 2	< 2	< 2	< 2	< 5	< 5
				Polyglycidyl Ether O-Cresol Formaldehyde								
				Novolac	29690-82-2	10-15						
				Phenolic Resin	9003-35-4	5-10						
				Sb2O3	1309-64-4	1-3						
				Brominated Epoxy resin	40039-93-8	1-3						
CHIP	Doped Silicon Glass Passivated	2.177	0.20%	Si Ni SiO2 PbO2 Al2O3	7440-21-3 7440-02-0 7631-86-9 1309-60-0 1344-28-1	84,3-85,7 0,83-1,25 6,7-7,0 6,3-6,5 0,57-0,85	< 2	43844 (**)	< 2	< 2	< 5	< 5
SOLDER PASTE	Pb/Sn5Ag2.5 Solder Paste	3.299	0.30%	Pb Sn Ag	7439-92-1 7440-31-5 7440-22-4	91,8 - 92,8 4,5 - 5,5 2,4-2,6	< 2	925013 (*)	< 2	< 2	< 5	< 5
COATING	Sn (100%)	13.998	1.27%	Sn Pb Cu Sb	7440-31-5 7439-92-1 7440-50-8 7440-36-0	99.85 0,05 max 0,05 max 0,05 max	< 2	< 2	< 2	< 2	< 5	< 5

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Supplier: Fagor Electrónica S. Coop Package: DO-201 AD

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COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
PRINTING INK	Pigments in Acrylate	0.200	0.02%	2- Propenic, polimer with 2-ethyl-2-(Hydroxymethyl)-1,3=propanediol and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione	53192-18-0	65-70	< 2	< 2	< 2	< 2	< 5	< 5
				Aluminum	7429-90-5	15-20						
				Silica	112945-52-5	1-5						
				Methanone,(1-hydroxycyclohexyl) Phenyl	947-19-3	1-5						
				Benzoic,acid,4-(dimethylamino)-2-ethylhexyl ester	21245-01-2	5-10						
WHOLE ITEM		1,100.000	100.00%									

Exception according to annex of Directive 2002/95/EC (RoHS):

* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

** Lead in glass of cathode ray tubes, electronic components and fluorescent tubes

